

Dimensions: Inches (mm)



Features

- 0603 Surface mount EMI suppression components
- Nickel barrier termination for excellent resistance to solder heat
- High current capacity
- Wide range of impedance values
- Multi layer technology
- Low DCR
- Flow and reflow soldering

Electrical

Impedance Range: HCB05 10Ω to 1500Ω

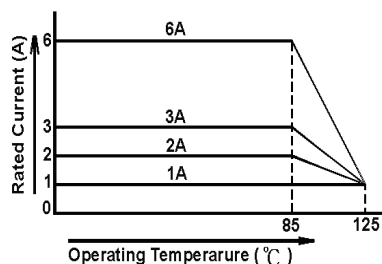
Tolerance: 25% over entire range

Operating Temp: -55°C ~ +125°C

Storage Temp: Under 25°C at 40~60% Humidity

Rate Current: Based on temp rise not to exceed 30°C

Rate current is derated as indicated below based on operating temp.



Resistance to Solder Heat

Pre-Heat 150°C, 1 minute

Solder Composition: Sn/Ag3.0/Cu0.5

Solder Temp: 260±5°C for 10sec ±1 sec.

Minimum of 75% of Electrode covered with new solder.

Impedance within 30% of initial value.

Allied Part Number	Impedance (Ω) @ 100MHz ±25%	DCR (Ω Max)	Rated Current (mA)
HCB05-100-RC	10	0.02	4000
HCB05-110-RC	11	0.02	4000
HCB05-190-RC	19	0.03	3000
HCB05-200-RC	20	0.03	3000
HCB05-220-RC	22	0.03	3000
HCB05-250-RC	25	0.03	3000
HCB05-300-RC	30	0.03	3000
HCB05-310-RC	31	0.035	3000
HCB05-400-RC	40	0.035	3000
HCB05-470-RC	47	0.04	3000
HCB05-500-RC	50	0.04	3000
HCB05-560-RC	56	0.04	3000
HCB05-600-RC	60	0.04	3000
HCB05-680-RC	68	0.05	2500
HCB05-700-RC	70	0.05	2500
HCB05-750-RC	75	0.05	2500
HCB05-800-RC	80	0.05	2500
HCB05-900-RC	90	0.05	2500
HCB05-101-RC	100	0.05	2500
HCB05-121-RC	120	0.08	2500
HCB05-151-RC	150	0.085	2000
HCB05-181-RC	180	0.09	2000
HCB05-201-RC	200	0.095	2000
HCB05-221-RC	220	0.1	2000
HCB05-241-RC	240	0.12	1500
HCB05-301-RC	300	0.12	1500
HCB05-331-RC	330	0.12	1500
HCB05-401-RC	400	0.12	1500
HCB05-471-RC	470	0.15	1500
HCB05-501-RC	500	0.15	1200
HCB05-601-RC	600	0.2	1000
HCB05-751-RC	750	0.25	800
HCB05-102-RC	1000	0.25	800
HCB05-152-RC	1500	0.4	500

All specifications subject to change without notice.

Test Equipment

(Z): HP4291A RF Impedance/Material Analyzer

(RDC): Chen Hwa 502BC

Physical

Packaging: 4000pcs per 7 inch reel.

Marking: None